

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT8070068

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DAISHI GONDO	06/13/2019
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18307040
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ATTORNEY DOCKET NUMBER:	MX-2019-PAT-0064-US-CON[2
NAME OF SUBMITTER:	MAHIKA SINGH
SIGNATURE:	/MAHIKA SINGH/
DATE SIGNED:	07/21/2023
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Daishi GONDO (individually, "Assignor"), has invented certain new and useful inventions for "CONNECTOR" for which a United States patent application ("Application") was filed on April 26, 2023, and accorded Serial No. 18/307,040 (Docket Number MX-2019-PAT-0064-US-CON[2]); and

WHEREAS, Molex Japan, LLC, a Limited Liability Company having a place of business at "1-5-4 Fukami-Higashi, Yamato, Kanagawa, 242-8585, JP" ("Assignee"), desires acquiring or has acquired Assignor's interest in the above-identified inventions, the Application, and any related U.S. or foreign patent applications and patents.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged:

Assignor hereby authorizes Assignee to file any of the above-referenced patent applications in the name of Assignee, and Assignor authorizes and requests the patent office of any country to issue any patent granted from any of the above-referenced patent applications in the name of Assignee;

Assignor further authorizes Assignee to insert the serial number and filing date of the Application into this Assignment if unknown upon execution of this Assignment;

Assignor by this Assignment does hereby sell, assign, and transfer, or by virtue of employment or applicable agreements has sold, assigned, and transferred, to Assignee, Assignor's entire right, title, and interest in and to the above-identified inventions and all improvements and modifications to the above-identified inventions, the Application, any U.S. or foreign patent applications related to the above-identified inventions, any U.S. or foreign patent applications claiming priority to any of the above-referenced patent applications, including any nonprovisional, divisional, continuation, continuation-in-part, reexamination, reissue, extension, substitution, or renewal of any of the above-referenced patent applications, any right to claim priority arising from or required for any of the above-referenced patent applications under any applicable convention, treaty, statute, or regulation, any other right, privilege, or form of protection related to the above-identified inventions or any of the above-referenced patent applications, and any U.S. or foreign patent granted from any of the above-referenced patent applications, to the full end of the term of the patent, to be held and enjoyed by Assignee as fully and entirely as it would have been held and enjoyed by Assignor, including the right to pursue, collect, and retain damages and any other remedies arising from any past, present, or future infringement of patents granted from the above-referenced patent applications;

Assignor hereby warrants and covenants that Assignor has not and will not execute any assignment or other instrument in conflict with this Assignment;

Assignor hereby covenants and agrees to perform any reasonable act that may be necessary or desirable to aid Assignee, its successors, legal representatives, and assigns, to obtain, maintain, and enforce protection in the U.S. and foreign countries for the above-identified inventions, above-referenced patent applications, and patents granted therefrom, including signing lawful papers, executing patent applications, making assignments, rightful oaths, and declarations, and testifying in judicial or administrative proceedings; and

Assignor and Assignee agree that this Assignment may be electronically signed, and that the electronic signatures appearing on this Assignment are the same as handwritten signatures for the purposes of validity, enforceability and admissibility.


Date: 06.13.2019

Daishi Gondo

Daishi GONDO

DECLARATION OF ACCEPTANCE

Assignee hereby acknowledges and accepts the aforementioned assignment of right, title, and interest and confirms consent that this Assignment may be recorded in appropriate patent offices.

/  _____ /

Jae Hoon Lee, Authorized Signatory on behalf of
Assignee: Molex Japan, LLC

Date: 6.13.2019